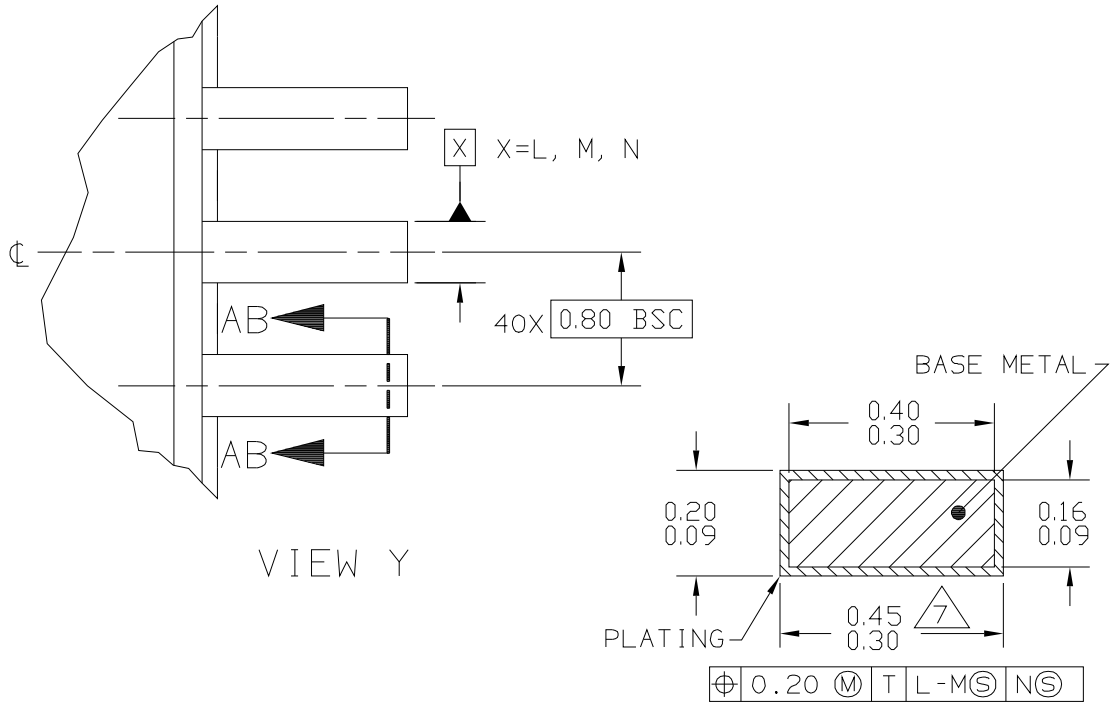
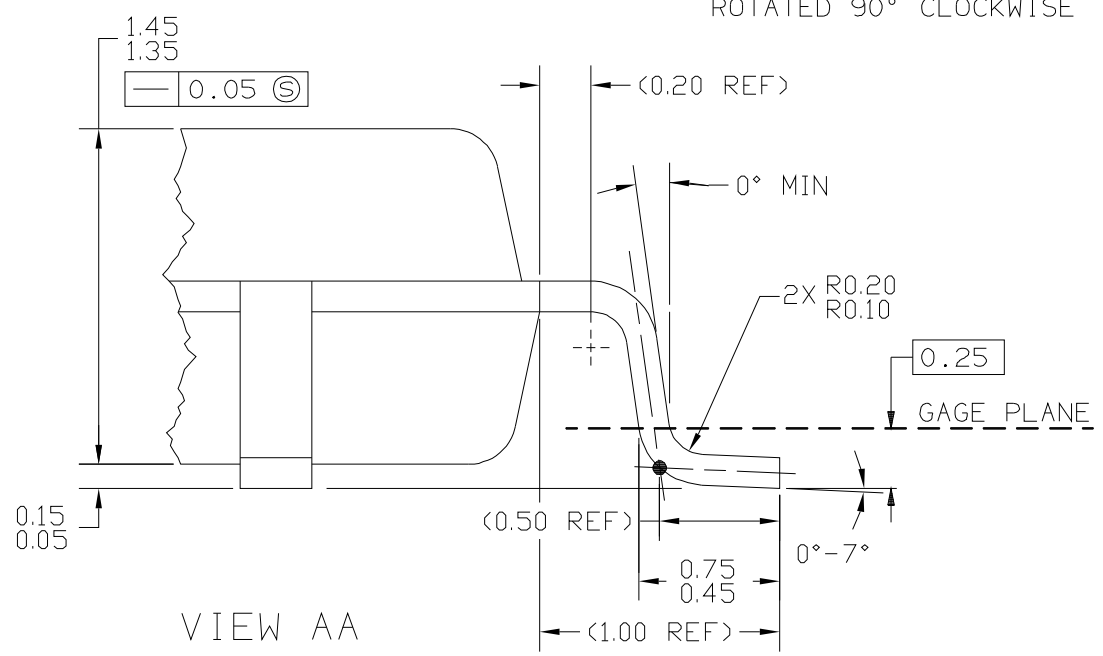


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TITLE: 44 LD LQFP, 10 X 10 PKG, 0.8 PITCH, 1.4 THICK		DOCUMENT NO: 98ASS23225W	REV: E
		STANDARD: JEDEC MS-026-BCB	
		SOT389-2	25 JAN 2016



SECTION AB-AB
ROTATED 90° CLOCKWISE



VIEW AA

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NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DATUM PLANE H IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS L, M AND N TO BE DETERMINED AT DATUM PLANE H.

△5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE T.

△6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

△7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE DIMENSION TO EXCEED 0.53. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07.

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